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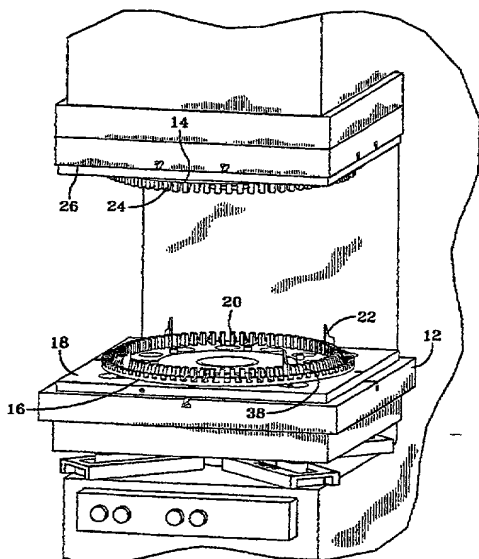
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(54) Title: BEAD CURING FINGER MOLD

(57) Abstract: A tire bundle is molded in a mold cavity formed by closing a mold having upper and lower mold halves with intermeshing fingers (20, 24) for enclosing bead wires and providing a molded bead ring for placing in a bead apex mold.



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